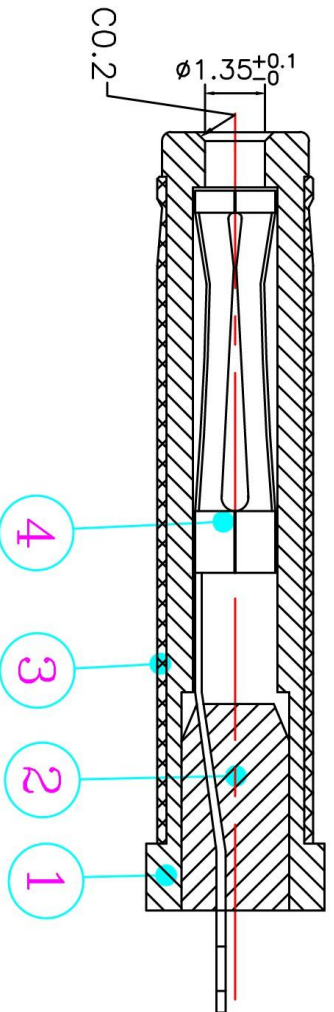
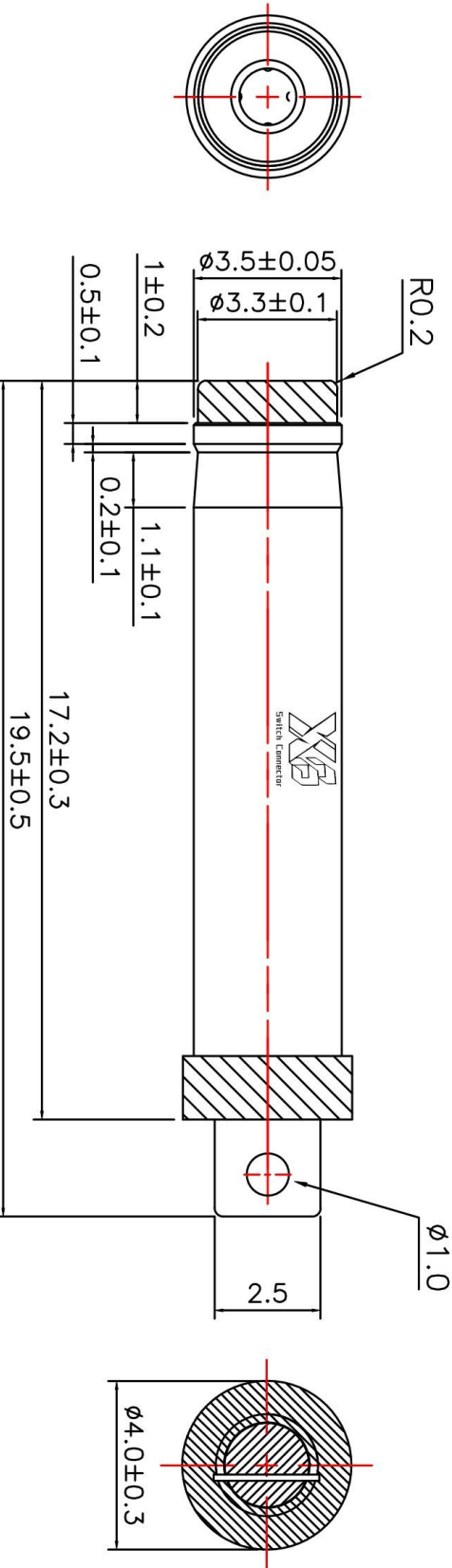




ROHS

REV	修正前	修正后	签名	日期
V1.0	新做制定		June	20200514



Technology Request:  
 1.Outlook:No burr, no hurt.  
 2.Electronic performance:  
 a:Insulation resistance: Above DC500V/100MΩ;  
 b:Endure voltage:AC500V at 1 minute;  
 c:Contact resistance:Under 30mΩ;  
 d:Rating: DC 30V 2A  
 3.Insertion force & withdrawal force:0.3-3kgf.  
 4.Salt spray test:24H.  
 5.Meet RoHS.  
 6.Remark \* is important specification.

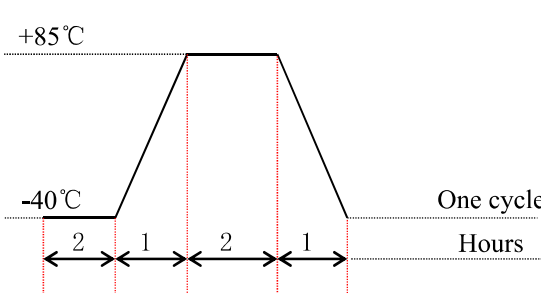
单位	一般公差	7
mm	The general tolerance	
比例	XX:±0.3	5
视图	X:X:±0.1	3
Third angle projection	.XX:±0.05	1
NO.		2
		3
		4

核准	校对	制图
APPROVED BY	CHECKED BY	DRAWN BY
June	杨义邦	李莹峰

规格	DESCRIPTION:
品名	P/N:
图号	DRAWN NO:
东莞市溪榜电子有限公司 DONG GUAN XI BANG ELECTRONI CS CO., LTD.	
规格	DC PLUG $\phi 3.5 \times \phi 1.35 \times 19.5$
品名	35135TV195
图号	CP-01-0051



ITEM 項目		TEST CONDITION 測試條件	PERFORMAENCE 性能
8.2	TERMINAL STRENGTH 端子強度	A static force of 300 g being applied in one direction on the tip of the terminal for 1 minute. 一個 300 克之靜負荷施加於端子頂部的一個方向持續1分鐘。	There shall be no sign of mechanical and electrical damage. 無任何迹象顯示機械及電器性能之損壞。
<b>9. DURABILITY 耐久性</b>			
9.1	SOLDERING TEST 可焊性試驗	The tip of the terminals shall be dipped 2 mm in the solder bath within temperature of 245±5°C for 3~5 seconds. 端子頂部被浸入焊錫池 2mm 深,溫度245±5°C, 時間3~5秒。	Over 95% of the immersed surface was covered by tin. 浸入的部份95%以上表面將被錫覆蓋。
		The condition mentioned is temperature for lead-free soldering . 無鉛錫測試 Alloy:Sn 96.5% Cu 3% Ag 0.5% 成份: 錫 96.5% 銅 3% 銀 0.5%	
9.2	SOLDERING RESISTANT TEST 耐焊性試驗	Dip soldering temperature 280±5°C,soldering time 3±0.5 seconds,immersion depth up to the surface of the board, thickness of PCB 1.6 mm. 浸錫爐的溫度控制在 280±5°C, 焊接的時間 3±0.5秒,於(基板)厚度為 1.6 mm.	Without deformation of case or excessive looseness of teminals, meet mechanical and electrical properties 本體無變形,能滿足於機械、電器性能.
		Manual soldering temperature 300±5°C, soldering time 3±0.5 seconds,however excessive pressure shall not be applied to the terminal. 手焊接的時候溫度需控制在300±5°C, 時間為 3±0.5秒,但不能在端子上施加異常壓力。	
		The condition mentioned is temperature for lead-free soldering . 無鉛錫測試。 Alloy:Sn 96.5% Cu 3% Ag 0.5% 成份: 錫 96.5% 銅 3% 銀 0.5%	
9.3	LIFE TEST 壽命試驗	5000 cycles of operation at a rate of 15-18 cycles per minute with unloading 無負載條件下,每分鐘 8-10 次的速度操作 5000 次。	(1) Contact resistance 100mΩ max. 接觸電阻100毫歐 以下 (2) Insertion force: 插入力度: 0.2~3.0kgf Extraction force: 拔出力度: 0.2~3.0kgf (3) ITEM 項目—7.2 (4) ITEM 項目—7.3 (5) ITEM 項目—8.2

ITEM 項目		TEST CONDITION 測試條件	PERFORMAENCE 性能
9.4	HEAT RESISTANT TEST 耐熱試驗	80±2℃ for 96 hours, test after keeping in normal condition for 30 minutes. 在 80±2℃ 環境中放96小時,再放在正常環境中30分鐘後進行測試。	(1) Contact resistance 100 mΩ max. 接觸電阻100毫歐以下  (2) Insulation resistance 50 MΩ min. 絕緣電阻50兆歐以上  (3) There shall be no sign of mechanical and electrical damage. 無任何迹象顯示機械及電器性能之損壞。
9.5	MOISTURE RESISTANT TEST 耐濕試驗	40±2℃ 90-95%RH for 96 hours, test after keeping in normal condition for 30 minutes. 在40±2℃ 90-95%RH 環境中放96小時,再放在正常環境中, 30分鐘後進行測試。	
9.6	COLD RESISTANT TEST 耐冷試驗	At -20±3℃ for 96 hours, test after keeping in normal condition for 30minutes. 在 -20±3℃ 環境中放96小時, 再置於正常環境中, 30分鐘後進行測試。	
9.7	TEMPERATURE CYCLING TEST 溫度交變試驗	According to following figure, after 5 cycles, test after keeping in normal condition for 30 minutes. 如圖示之環境中, 循環5次後, 再置於正常環境中, 30分鐘後進行測試。  	
9.8	SALT MIST TEST 鹽霧試驗	Wash and dry after the testing 24h under the conditions indicated below. 在如下環境中試驗24小時後, 進行清洗乾燥後測試。 Temperature(溫度):35℃±2℃ Water Salinity(鹽水濃度):5±1% (by weight, 重量比)	There shall be no obvious rust on metal parts. 金屬部分沒有明顯生銹跡象。

<p>9.9</p>	<p>STORAGE ENVIROMENT 儲存環境</p>	<p>Under sealing pack condition,stored temperature don't exceed 30°C and relative humidity is 75% RH; in the enviroment of no sunshine direct and no corrosive gas,the stored time ought to be three months but within six month at most. 密封包裝狀態下，儲存溫度為≤30°C，相對溫度75% RH; 無陽光直射，無腐蝕性氣體的環境中，儲存時間為3個月，最長不宜超過6個月。</p> <p>Without sealing pack condition,stored temperature don't exceed 30°C and relative humidity is 75% RH; in the enviroment of no sunshine direct and no corrosive gas,the stored time shouldn't exceed 48H 無密封包裝狀態下，儲存溫度為≤30°C，相對溫度75% RH; 無陽光直射，無腐蝕性氣體的環境中，儲存時間最長不宜超過48小時。</p> <p>Don't excessive overlap or overstocking when keeping this goods,in case of damage. 保存時應注意物品不能過量重疊、積壓、以免損壞</p>	
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